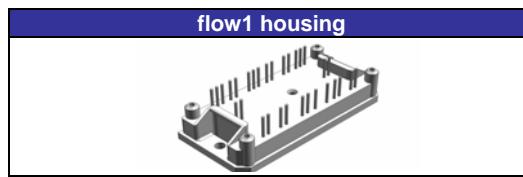
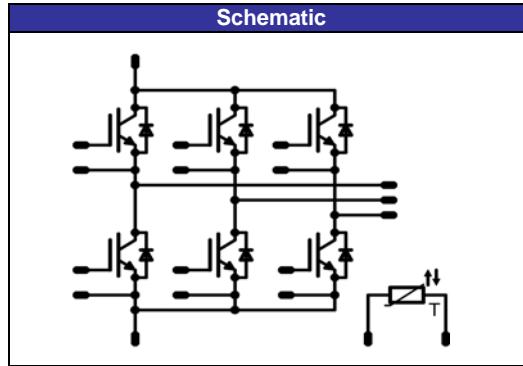


**flowPACK 1 3rd gen**
**600V/100A**

Features
• Compact flow1 housing
• Trench Fieldstop IGBT3 Technology
• Compact and Low Inductance Design
• AlN substrate for improved performance
• Built-in NTC



Target Applications
• Motor Drive
• Power Generation
• UPS



Types
• V23990-P825-F

## Maximum Ratings

 $T_j=25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

**Inverter Transistor**

Collector-emitter break down voltage	$V_{CE}$		600	V
DC collector current	$I_C$	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	100	A
Repetitive peak collector current	$I_{Cpulse}$	$t_p$ limited by $T_{j\max}$	300	A
Power dissipation per IGBT	$P_{tot}$	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	190	W
Gate-emitter peak voltage	$V_{GE}$		$\pm 20$	V
Short circuit ratings	$t_{SC}$ $V_{CC}$	$T_j \leq 150^\circ\text{C}$ $V_{GE}=15\text{V}$	6 360	$\mu\text{s}$ V
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

**Inverter Diode**

Peak Repetitive Reverse Voltage	$V_{RRM}$	$T_j=25^\circ\text{C}$	600	V
DC forward current	$I_F$	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	94	A
Repetitive peak forward current	$I_{FRM}$	$t_p$ limited by $T_{j\max}$	300	A
Power dissipation per Diode	$P_{tot}$	$T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$	139	W
Maximum Junction Temperature	$T_{j\max}$		175	$^\circ\text{C}$

## Maximum Ratings

T<sub>j</sub>=25°C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

### Thermal Properties

Storage temperature	T <sub>stg</sub>		-40...+125	°C
Operation temperature under switching condition	T <sub>op</sub>		-40...+150	°C

### Insulation Properties

Insulation voltage	V <sub>is</sub>	t=2 s	DC voltage	4000	V
Creepage distance				min 12,7	mm
Clearance				min 12,7	mm

**Characteristic Values**

Parameter	Symbol	Conditions				Value			Unit
			$V_{GE}$ [V] or $V_{GS}$ [V]	$V_r$ [V] or $V_{CE}$ [V] or $V_{DS}$ [V]	$I_c$ [A] or $I_F$ [A] or $I_D$ [A]	$T_j$	Min	Typ	Max

**Inverter Transistor**

Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0016	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	5	5,8	6,5	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		100	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1,1	1,54 1,76	2,25	V
Collector-emitter cut-off current incl. Diode	$I_{CES}$		0	600		$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$			0,66	mA
Gate-emitter leakage current	$I_{GES}$		20	0		$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$			650	nA
Integrated Gate resistor	$R_{gint}$							2		$\Omega$
Turn-on delay time	$t_{d(on)}$	$R_{goff}=4 \Omega$ $R_{gon}=4 \Omega$	$\pm 15$	300	100	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		151 157		ns
Rise time	$t_r$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		19 25		
Turn-off delay time	$t_{d(off)}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		205 232		
Fall time	$t_f$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		89 101		
Turn-on energy loss per pulse	$E_{on}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		1,34 2,00		mWs
Turn-off energy loss per pulse	$E_{off}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		2,35 3,11		
Input capacitance	$C_{ies}$							6160		pF
Output capacitance	$C_{oss}$							384		
Reverse transfer capacitance	$C_{rss}$							183		
Gate charge	$Q_{Gate}$	$V_{CC}=480\text{V}$	$\pm 15$		100	$T_j=25^\circ\text{C}$		625		nC
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um Kunze foil KU-ALF5						0,50		K/W

**Inverter Diode**

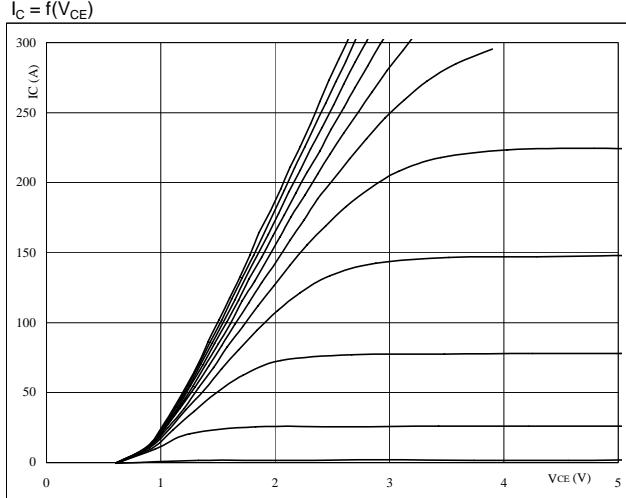
Diode forward voltage	$V_F$				100	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1,2	1,65 1,53	2,4	V
Peak reverse recovery current	$I_{RRM}$	$R_{gon}=4 \Omega$	$\pm 15$	300	100	$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		97 117		A
Reverse recovery time	$t_{rr}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		140 292		ns
Reverse recovered charge	$Q_{rr}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		4,87 10,01		$\mu\text{C}$
Peak rate of fall of recovery current	$d(i_{rec})/\text{max dt}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		6149 3433		$\text{A}/\mu\text{s}$
Reverse recovered energy	$E_{rec}$					$T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$		1,03 2,25		mWs
Thermal resistance chip to heatsink per chip	$R_{thJH}$	Thermal foil thickness=76um Kunze foil KU-ALF5						0,68		K/W

**Thermistor**

Rated resistance	$R_{25}$	Tol. $\pm 5\%$				$T_j=25^\circ\text{C}$	4,2	4,7	5,8	$\text{k}\Omega$
Deviation of R100	$D_{RR}$	$R_{100}=435\Omega$				$T_c=100^\circ\text{C}$		2,6		$^{\circ}\text{K}/\text{K}$
Power dissipation given Epcos-Typ	P					$T_j=25^\circ\text{C}$		210		mW
B-value	$B_{(25/100)}$	Tol. $\pm 3\%$				$T_j=25^\circ\text{C}$		3530		K

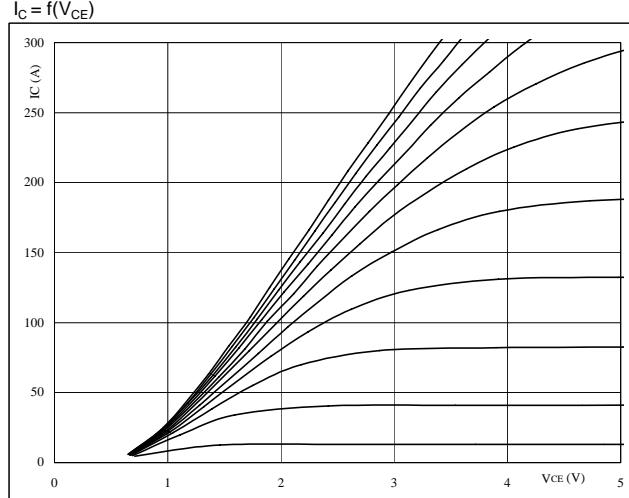
## Output Inverter

**Figure 1**  
Typical output characteristics  
 $I_C = f(V_{CE})$



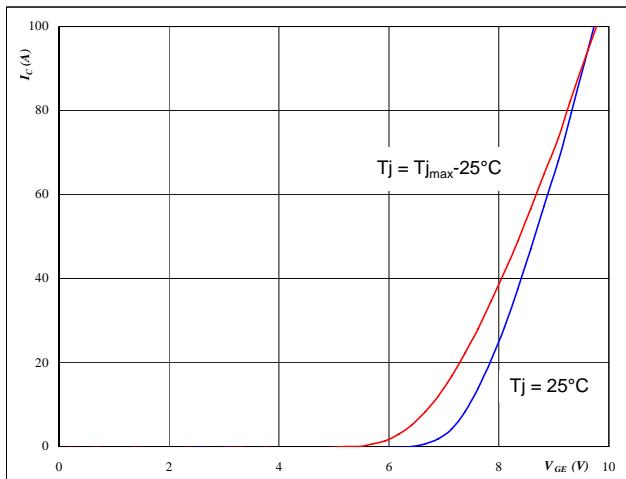
**At**  
 $t_p = 250 \mu s$   
 $T_j = 25 {}^\circ C$   
 VGE from 7 V to 17 V in steps of 1 V

**Figure 2**  
Typical output characteristics  
 $I_C = f(V_{CE})$



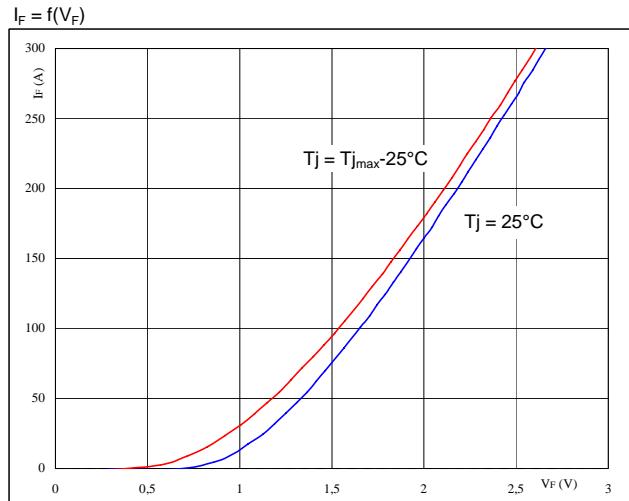
**At**  
 $t_p = 250 \mu s$   
 $T_j = 150 {}^\circ C$   
 VGE from 7 V to 17 V in steps of 1 V

**Figure 3**  
Typical transfer characteristics  
 $I_C = f(V_{GE})$



**At**  
 $t_p = 250 \mu s$   
 $V_{CE} = 10 V$

**Figure 4**  
Typical diode forward current as  
a function of forward voltage  
 $I_F = f(V_F)$



**At**  
 $t_p = 250 \mu s$

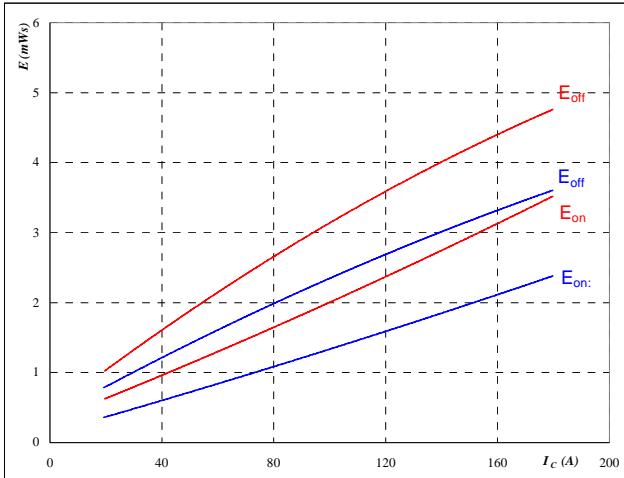
## Output Inverter

**Figure 5**

Output inverter IGBT

**Typical switching energy losses  
as a function of collector current**

$$E = f(I_c)$$



With an inductive load at

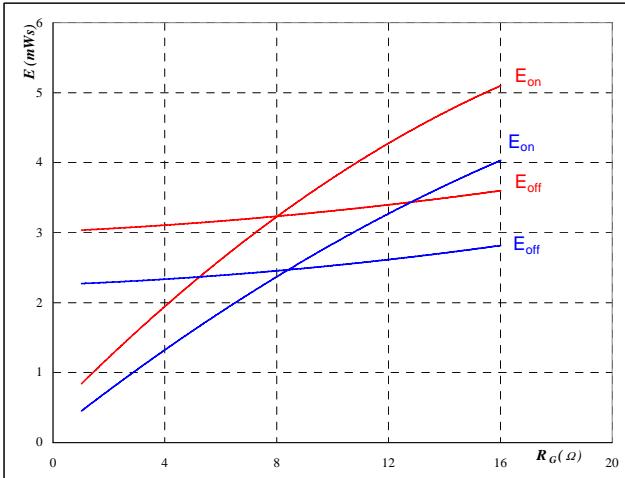
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 300 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 4 \quad \Omega \\ R_{goff} &= 4 \quad \Omega \end{aligned}$$

**Figure 6**

Output inverter IGBT

**Typical switching energy losses  
as a function of gate resistor**

$$E = f(R_G)$$



With an inductive load at

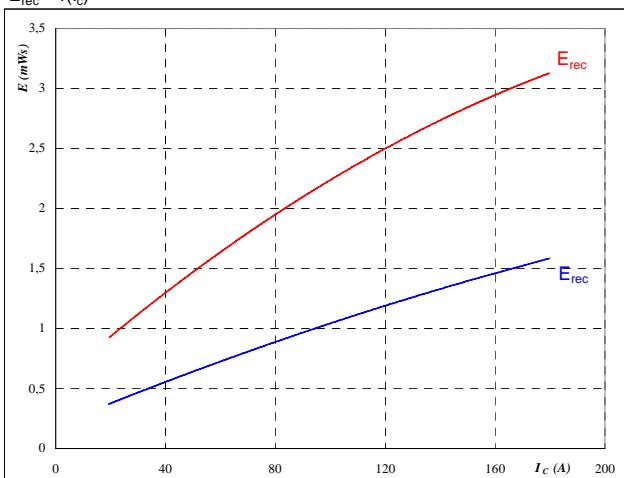
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 300 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_c &= 100 \quad \text{A} \end{aligned}$$

**Figure 7**

Output inverter IGBT

**Typical reverse recovery energy loss  
as a function of collector current**

$$E_{rec} = f(I_c)$$



With an inductive load at

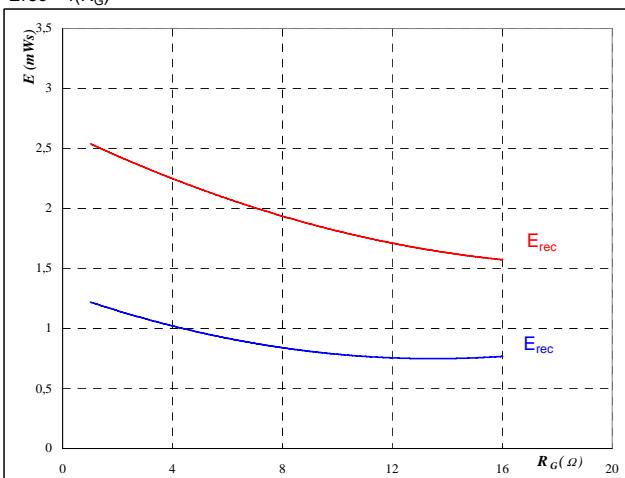
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 300 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 4 \quad \Omega \end{aligned}$$

**Figure 8**

Output inverter IGBT

**Typical reverse recovery energy loss  
as a function of gate resistor**

$$E_{rec} = f(R_G)$$



With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 300 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_c &= 100 \quad \text{A} \end{aligned}$$

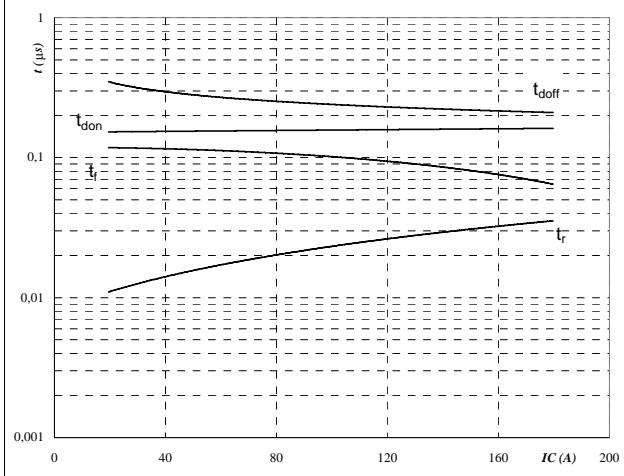
## Output Inverter

**Figure 9**

Output inverter IGBT

**Typical switching times as a function of collector current**

$$t = f(I_C)$$



With an inductive load at

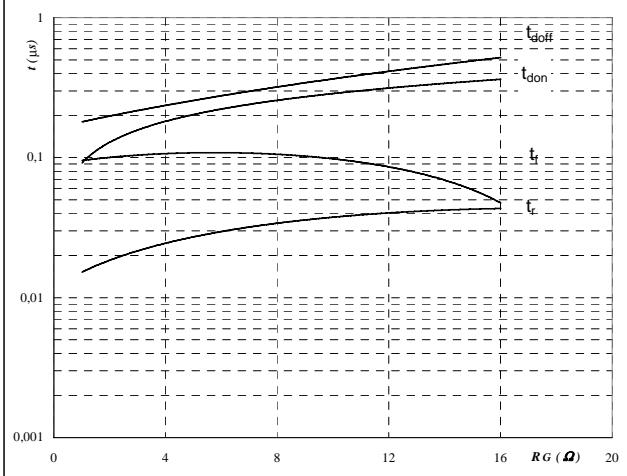
$T_j =$	150	°C
$V_{CE} =$	300	V
$V_{GE} =$	$\pm 15$	V
$R_{gon} =$	4	Ω
$R_{goff} =$	4	Ω

**Figure 10**

Output inverter IGBT

**Typical switching times as a function of gate resistor**

$$t = f(R_G)$$



With an inductive load at

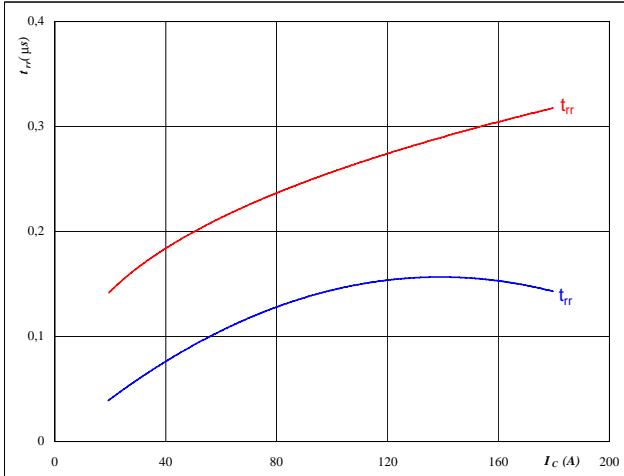
$T_j =$	150	°C
$V_{CE} =$	300	V
$V_{GE} =$	$\pm 15$	V
$I_C =$	100	A

**Figure 11**

Output inverter FRED

**Typical reverse recovery time as a function of collector current**

$$t_{rr} = f(I_C)$$



At

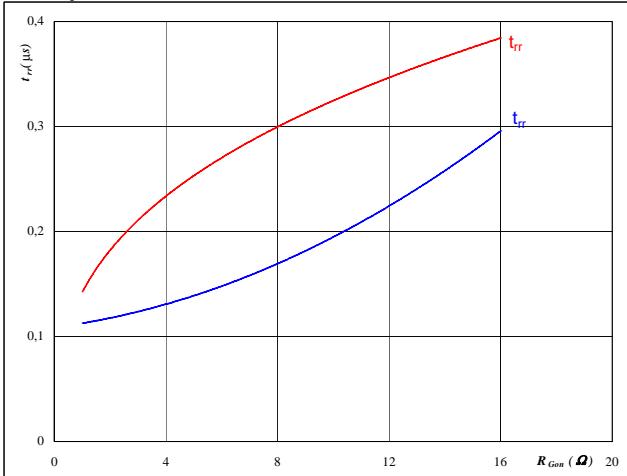
$T_j =$	25/150	°C
$V_{CE} =$	300	V
$V_{GE} =$	$\pm 15$	V
$R_{gon} =$	4	Ω

**Figure 12**

Output inverter FRED

**Typical reverse recovery time as a function of IGBT turn on gate resistor**

$$t_{rr} = f(R_{Gon})$$



At

$T_j =$	25/150	°C
$V_R =$	300	V
$I_F =$	100	A
$V_{GE} =$	$\pm 15$	V

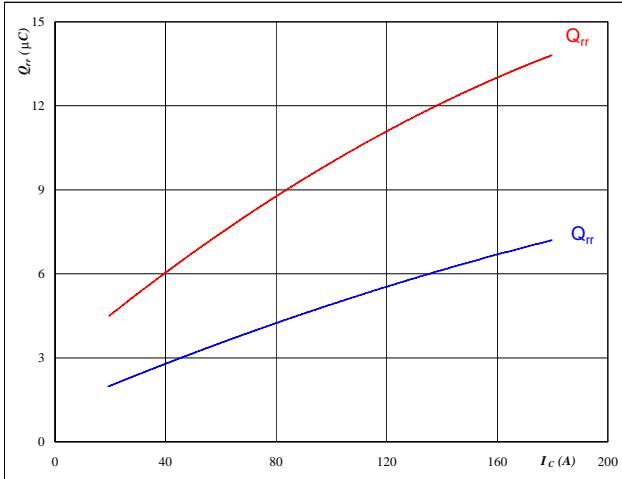
## Output Inverter

**Figure 13**

Output inverter FRED

**Typical reverse recovery charge as a function of collector current**

$$Q_{rr} = f(I_c)$$

**At**

$$T_j = 25/150 \quad ^\circ C$$

$$V_{CE} = 300 \quad V$$

$$V_{GE} = \pm 15 \quad V$$

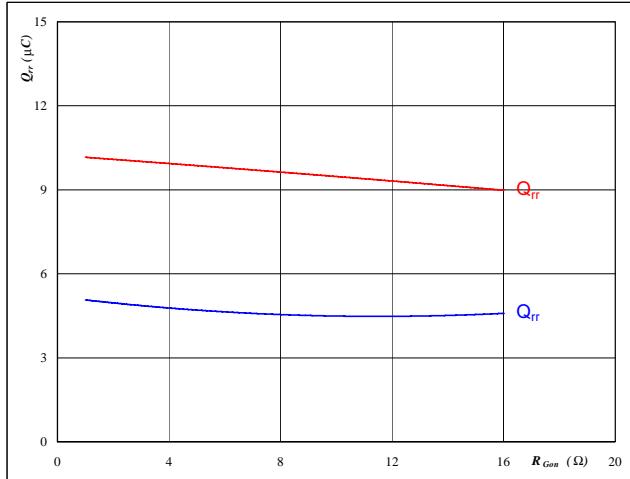
$$R_{gon} = 4 \quad \Omega$$

**Figure 14**

Output inverter FRED

**Typical reverse recovery charge as a function of IGBT turn on gate resistor**

$$Q_{rr} = f(R_{gon})$$

**At**

$$T_j = 25/150 \quad ^\circ C$$

$$V_R = 300 \quad V$$

$$I_F = 100 \quad A$$

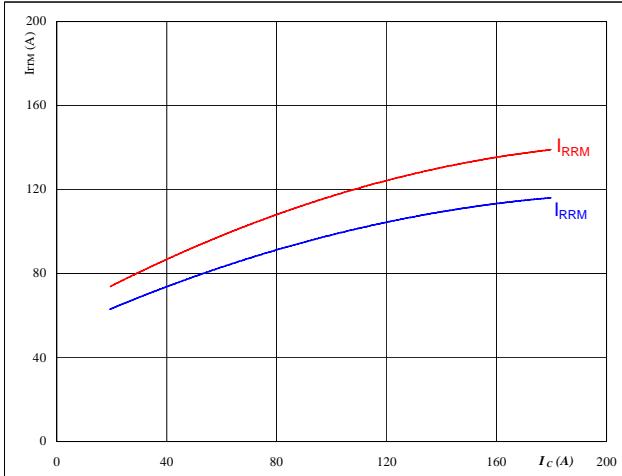
$$V_{GE} = \pm 15 \quad V$$

**Figure 15**

Output inverter FRED

**Typical reverse recovery current as a function of collector current**

$$I_{RRM} = f(I_c)$$

**At**

$$T_j = 25/150 \quad ^\circ C$$

$$V_{CE} = 300 \quad V$$

$$V_{GE} = \pm 15 \quad V$$

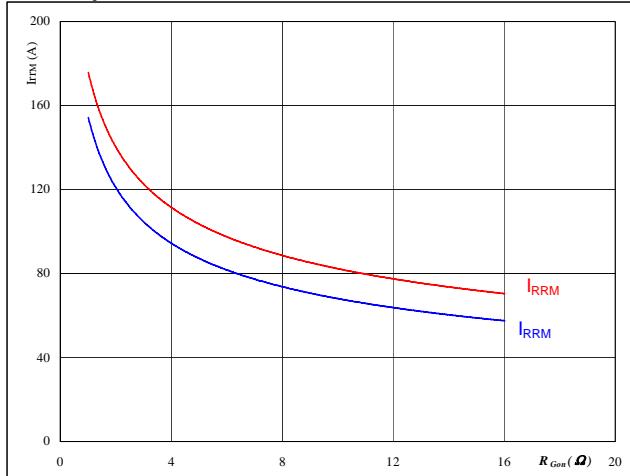
$$R_{gon} = 4 \quad \Omega$$

**Figure 16**

Output inverter FRED

**Typical reverse recovery current as a function of IGBT turn on gate resistor**

$$I_{RRM} = f(R_{gon})$$

**At**

$$T_j = 25/150 \quad ^\circ C$$

$$V_R = 300 \quad V$$

$$I_F = 100 \quad A$$

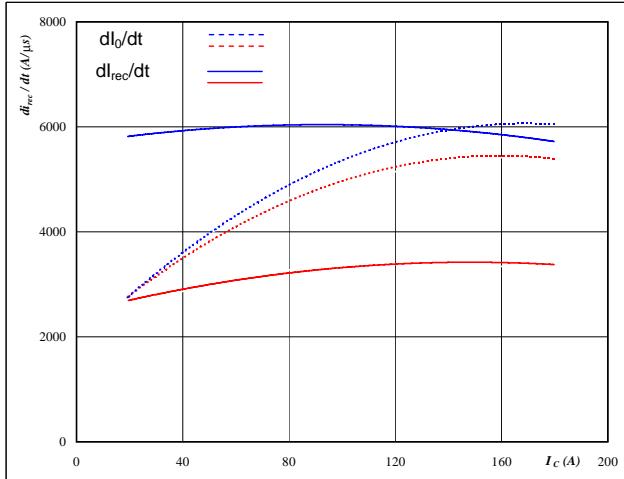
$$V_{GE} = \pm 15 \quad V$$

## Output Inverter

**Figure 17**

Output inverter FRED

**Typical rate of fall of forward  
and reverse recovery current as a  
function of collector current**  
 $dI_0/dt, dI_{rec}/dt = f(I_C)$

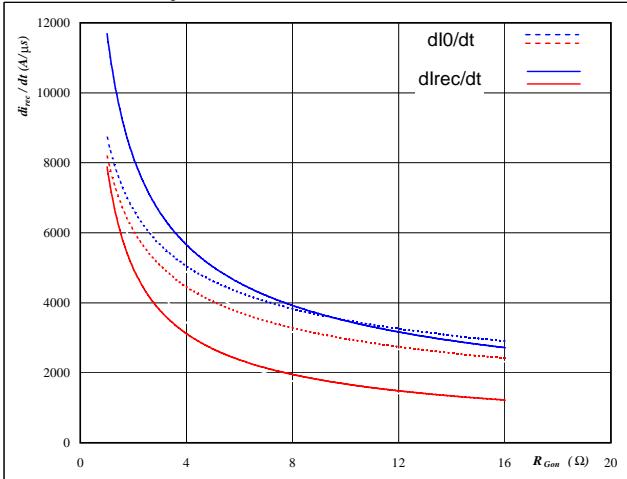
**At**

$T_j = 25/150 \text{ } ^\circ\text{C}$   
 $V_{CE} = 300 \text{ V}$   
 $V_{GE} = \pm 15 \text{ V}$   
 $R_{Gon} = 4 \Omega$

**Figure 18**

Output inverter FRED

**Typical rate of fall of forward  
and reverse recovery current as a  
function of IGBT turn on gate resistor**  
 $dI_0/dt, dI_{rec}/dt = f(R_{Gon})$

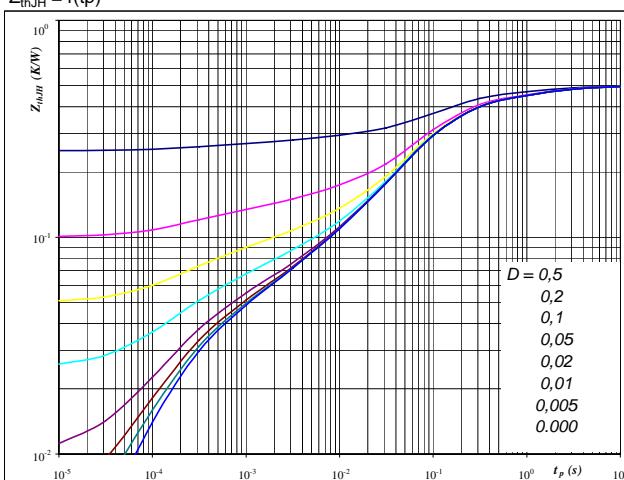
**At**

$T_j = 25/150 \text{ } ^\circ\text{C}$   
 $V_R = 300 \text{ V}$   
 $I_F = 100 \text{ A}$   
 $V_{GE} = \pm 15 \text{ V}$

**Figure 19**

Output inverter IGBT

**IGBT transient thermal impedance  
as a function of pulse width**  
 $Z_{thJH} = f(t_p)$

**At**

$D = t_p / T$   
 $R_{thJH} = 0,50 \text{ K/W}$

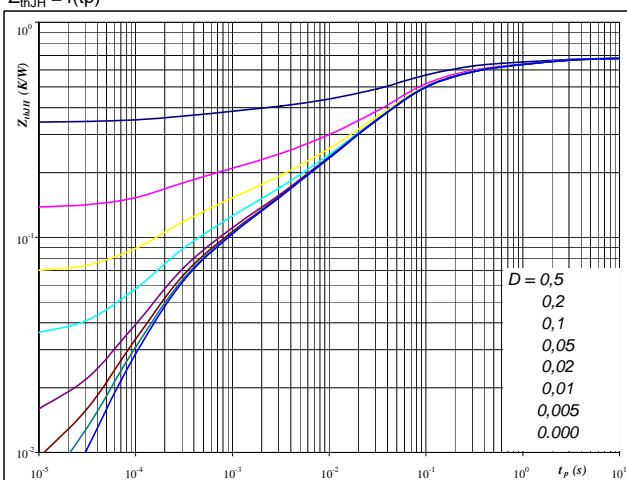
IGBT thermal model values

R (C/W)	Tau (s)
0,02	1,0E+01
0,08	1,3E+00
0,17	1,6E-01
0,16	5,7E-02
0,03	5,3E-03
0,02	7,6E-04
0,02	1,6E-04

**Figure 20**

Output inverter FRED

**FRED transient thermal impedance  
as a function of pulse width**  
 $Z_{thJH} = f(t_p)$

**At**

$D = t_p / T$   
 $R_{thJH} = 0,68 \text{ K/W}$

FRED thermal model values

R (C/W)	Tau (s)
0,02	1,0E+01
0,08	1,3E+00
0,13	1,6E-01
0,27	4,3E-02
0,08	6,0E-03
0,05	9,5E-04
0,05	1,9E-04

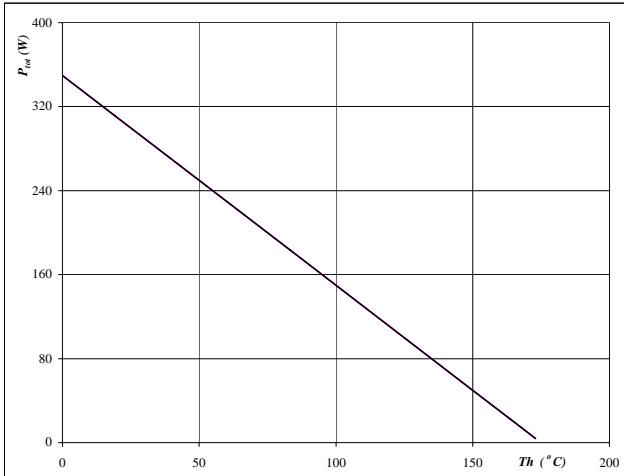
## Output Inverter

**Figure 21**

Output inverter IGBT

**Power dissipation as a function of heatsink temperature**

$$P_{\text{tot}} = f(T_h)$$

**At**

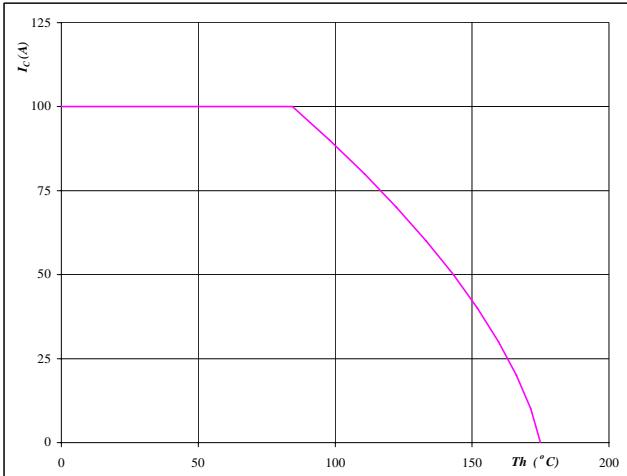
$$T_j = 175 \quad {}^\circ\text{C}$$

**Figure 22**

Output inverter IGBT

**Collector current as a function of heatsink temperature**

$$I_C = f(T_h)$$

**At**

$$T_j = 175 \quad {}^\circ\text{C}$$

$$V_{GE} = 15 \quad \text{V}$$

**Figure 23**

Output inverter FRED

**Power dissipation as a function of heatsink temperature**

$$P_{\text{tot}} = f(T_h)$$

**At**

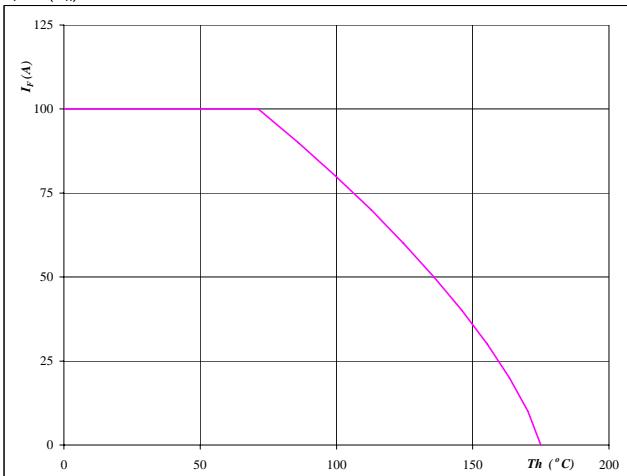
$$T_j = 175 \quad {}^\circ\text{C}$$

**Figure 24**

Output inverter FRED

**Forward current as a function of heatsink temperature**

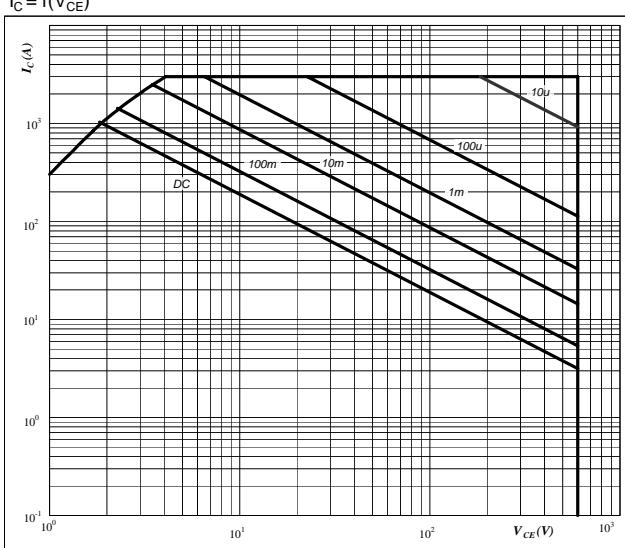
$$I_F = f(T_h)$$

**At**

$$T_j = 175 \quad {}^\circ\text{C}$$

## Output Inverter

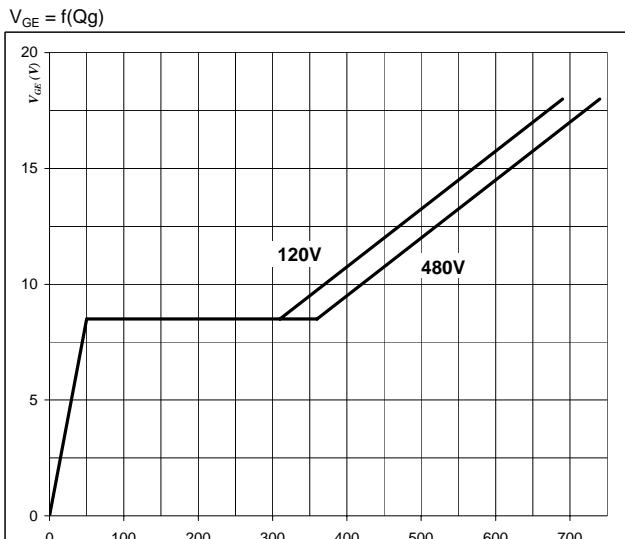
**Figure 25**  
Safe operating area as a function  
of collector-emitter voltage  
 $I_C = f(V_{CE})$



**At**  
 $D =$  single pulse  
 $T_h =$  80  $^{\circ}\text{C}$   
 $V_{GE} =$   $\pm 15$  V  
 $T_j =$   $T_{j\max}$   $^{\circ}\text{C}$

Output inverter IGBT

**Figure 26**  
Gate voltage vs Gate charge  
 $V_{GE} = f(Qg)$



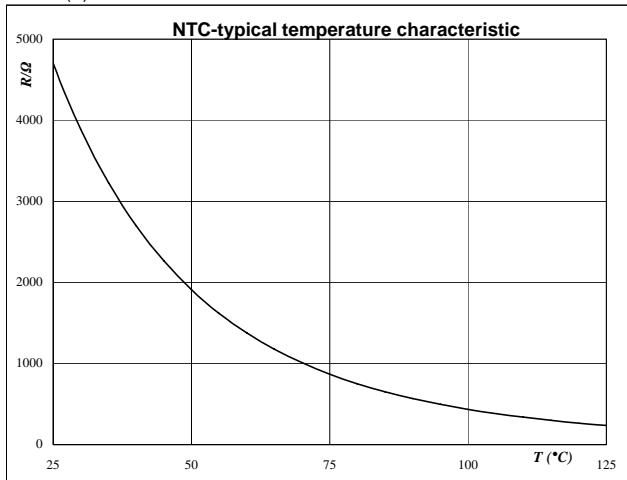
**At**  
 $I_C =$  100 A

**Thermistor****Figure 1**

Thermistor

Typical NTC characteristic  
as a function of temperature

$$R_T = f(T)$$



## Switching Definitions Output Inverter

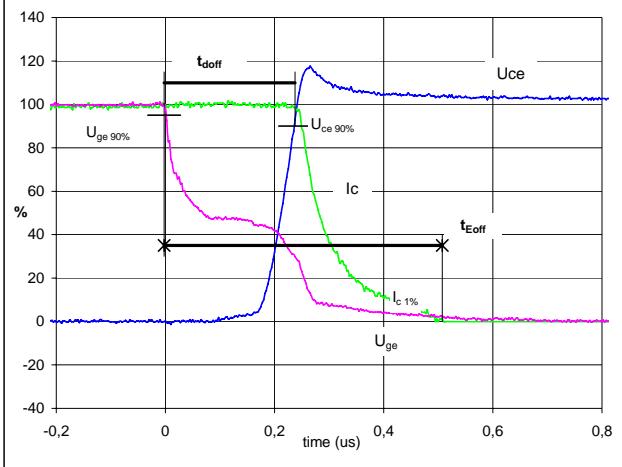
**General conditions**

$T_j$	=	150 °C
$R_{gon}$	=	4 Ω
$R_{goff}$	=	4 Ω

**Figure 1**

Output inverter IGBT

**Turn-off Switching Waveforms & definition of  $t_{doff}$ ,  $t_{Eoff}$**   
 $(t_{Eoff} = \text{integrating time for } E_{off})$

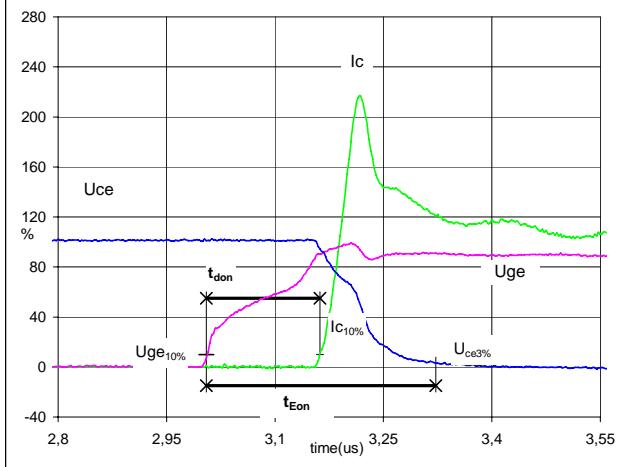


$V_{GE}(0\%) = -15$  V  
 $V_{GE}(100\%) = 15$  V  
 $V_C(100\%) = 300$  V  
 $I_C(100\%) = 99$  A  
 $t_{doff} = 0,23$  μs  
 $t_{Eoff} = 0,51$  μs

**Figure 2**

Output inverter IGBT

**Turn-on Switching Waveforms & definition of  $t_{don}$ ,  $t_{Eon}$**   
 $(t_{Eon} = \text{integrating time for } E_{on})$

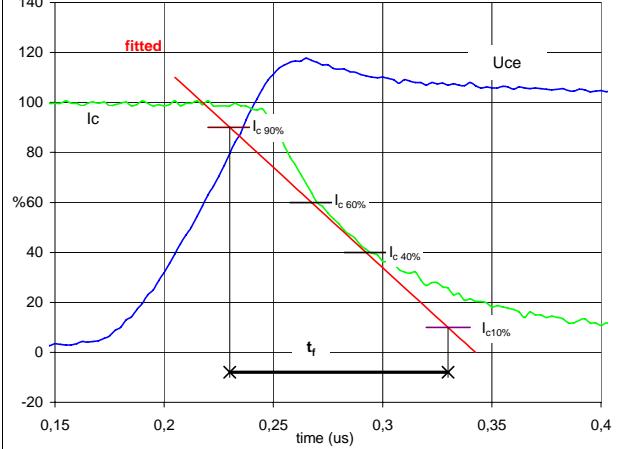


$V_{GE}(0\%) = -15$  V  
 $V_{GE}(100\%) = 15$  V  
 $V_C(100\%) = 300$  V  
 $I_C(100\%) = 99$  A  
 $t_{don} = 0,16$  μs  
 $t_{Eon} = 0,32$  μs

**Figure 3**

Output inverter IGBT

**Turn-off Switching Waveforms & definition of  $t_f$**

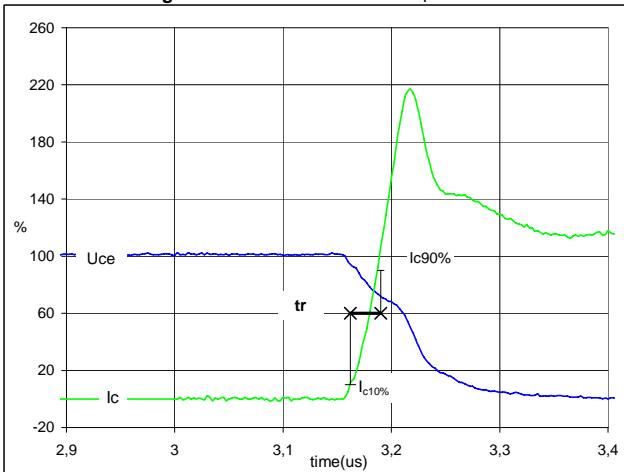


$V_C(100\%) = 300$  V  
 $I_C(100\%) = 99$  A  
 $t_f = 0,10$  μs

**Figure 4**

Output inverter IGBT

**Turn-on Switching Waveforms & definition of  $t_r$**

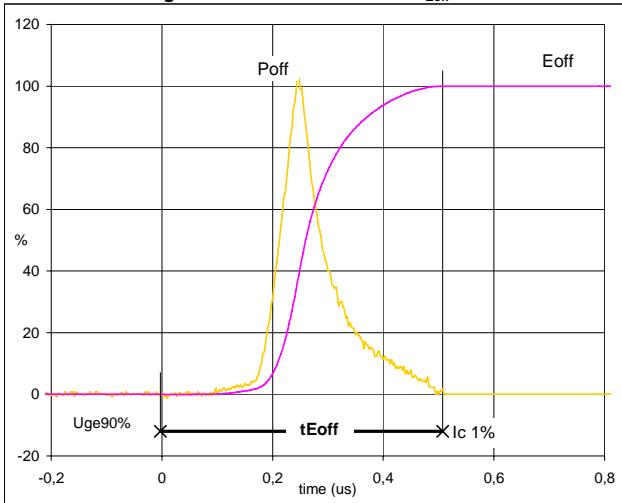


$V_C(100\%) = 300$  V  
 $I_C(100\%) = 99$  A  
 $t_r = 0,03$  μs

## Switching Definitions Output Inverter

**Figure 5**

Output inverter IGBT

Turn-off Switching Waveforms & definition of  $t_{Eoff}$ 

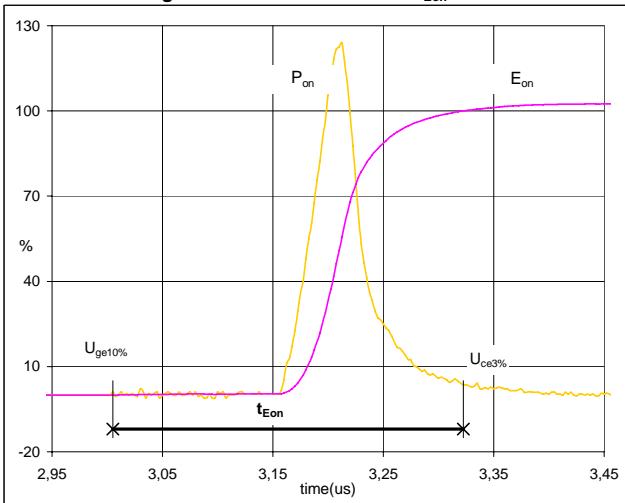
$$P_{off} (100\%) = 29,79 \text{ kW}$$

$$E_{off} (100\%) = 3,11 \text{ mJ}$$

$$t_{Eoff} = 0,51 \mu\text{s}$$

**Figure 6**

Output inverter IGBT

Turn-on Switching Waveforms & definition of  $t_{Eon}$ 

$$P_{on} (100\%) = 29,79 \text{ kW}$$

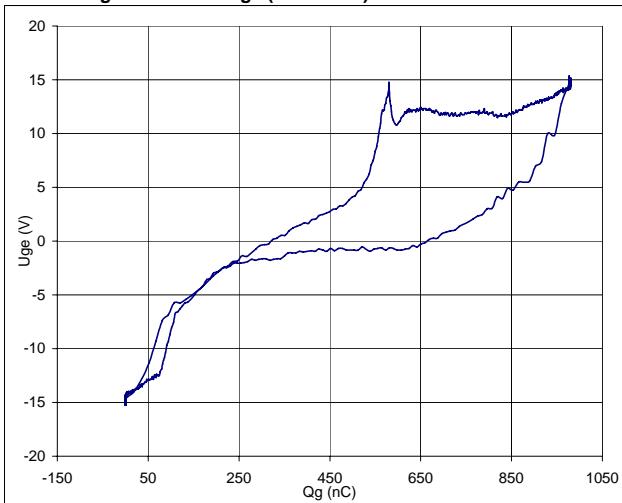
$$E_{on} (100\%) = 2,00 \text{ mJ}$$

$$t_{Eon} = 0,32 \mu\text{s}$$

**Figure 7**

Output inverter FRED

Gate voltage vs Gate charge (measured)



$$V_{GEoff} = -15 \text{ V}$$

$$V_{GEon} = 15 \text{ V}$$

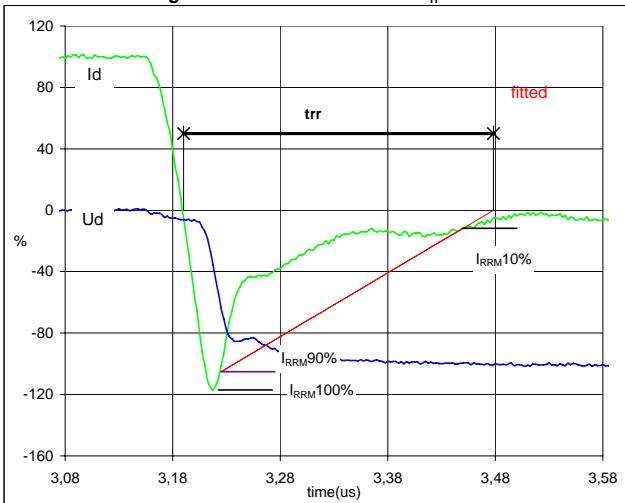
$$V_C (100\%) = 300 \text{ V}$$

$$I_C (100\%) = 99 \text{ A}$$

$$Q_g = 979,79 \text{ nC}$$

**Figure 8**

Output inverter IGBT

Turn-off Switching Waveforms & definition of  $t_{trr}$ 

$$V_d (100\%) = 300 \text{ V}$$

$$I_d (100\%) = 99 \text{ A}$$

$$I_{RRM} (100\%) = -117 \text{ A}$$

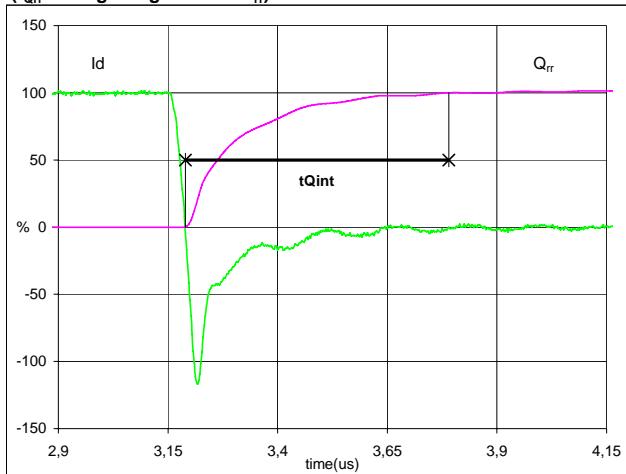
$$t_{trr} = 0,29 \mu\text{s}$$

## Switching Definitions Output Inverter

**Figure 9**

Output inverter FRED

**Turn-on Switching Waveforms & definition of  $t_{Qrr}$**   
 $(t_{Qrr} = \text{integrating time for } Q_{rr})$

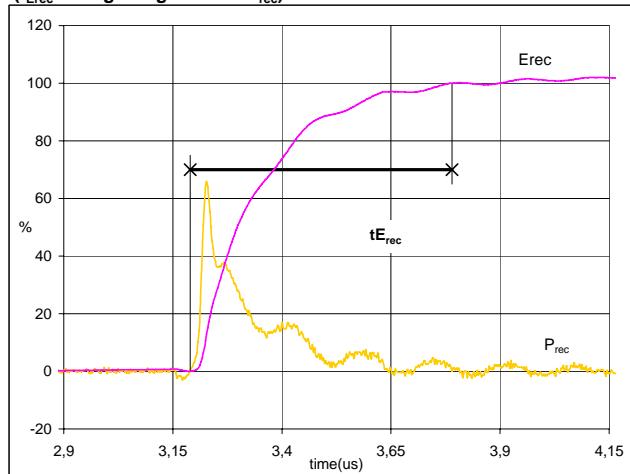


$I_d(100\%) = 99 \text{ A}$   
 $Q_{rr}(100\%) = 10,01 \mu\text{C}$   
 $t_{Qint} = 0,60 \mu\text{s}$

**Figure 10**

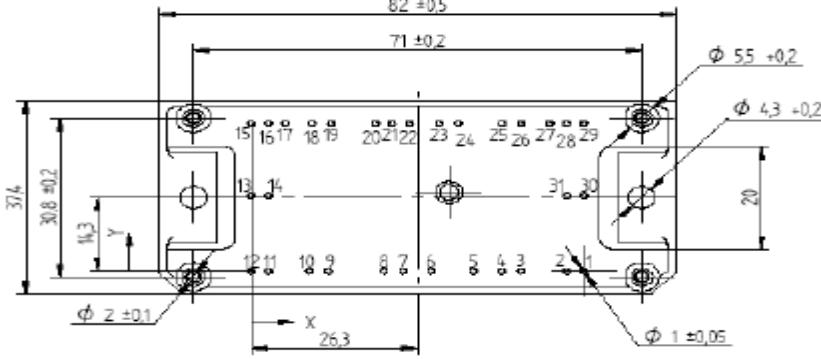
Output inverter FRED

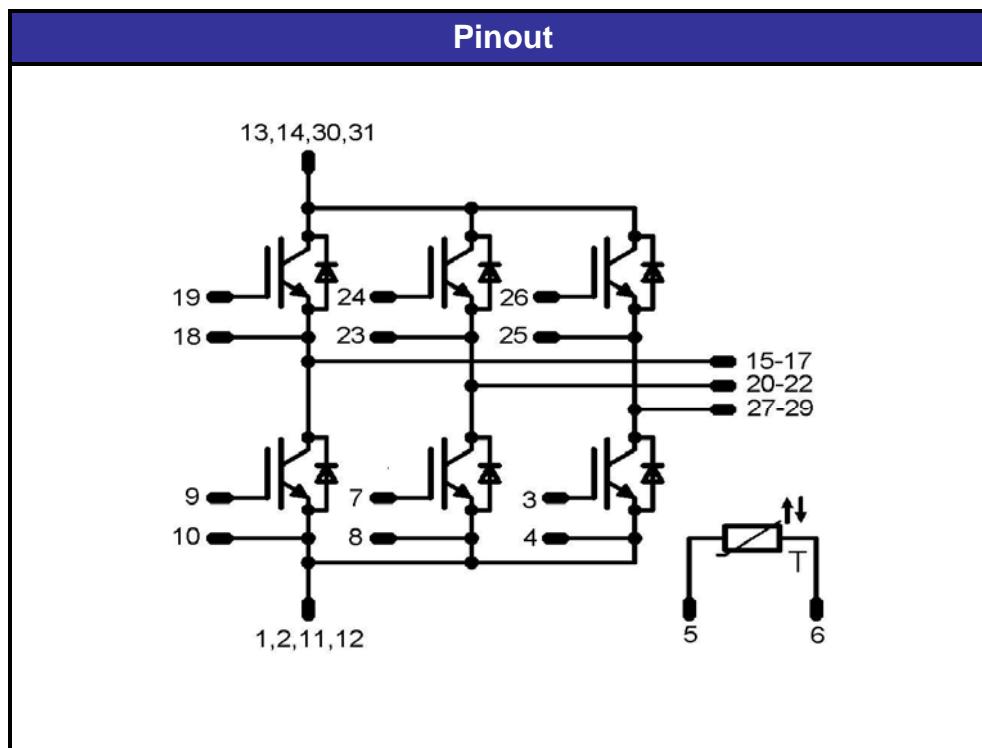
**Turn-on Switching Waveforms & definition of  $t_{Erec}$**   
 $(t_{Erec} = \text{integrating time for } E_{rec})$



$P_{rec}(100\%) = 29,79 \text{ kW}$   
 $E_{rec}(100\%) = 2,25 \text{ mJ}$   
 $t_{Erec} = 0,60 \mu\text{s}$

## Package Outline and Pinout

Outline											
											
Pin Table											
Pin	X	Y	Pin	X	Y	Pin	X	Y	Pin	X	Y
1	52,6	0	9	12,2	0	17	5,4	28,6	25	39,7	28,6
2	49,9	0	10	9,2	0	18	9,6	28,6	26	42,7	28,6
3	42,65	0	11	2,7	0	19	12,6	28,6	27	47,2	28,6
4	39,65	0	12	0	0	20	19,6	28,6	28	49,9	28,6
5	35,15	0	13	0	14,65	21	22,3	28,6	29	52,6	28,6
6	28,4	0	14	2,7	14,65	22	25	28,6	30	52,6	14,65
7	24	0	15	0	28,6	23	29,7	28,6	31	49,9	14,65
8	21	0	16	2,7	28,6	24	32,7	28,6			



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Datasheet Status	Product Status	Definition
Target	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff.
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